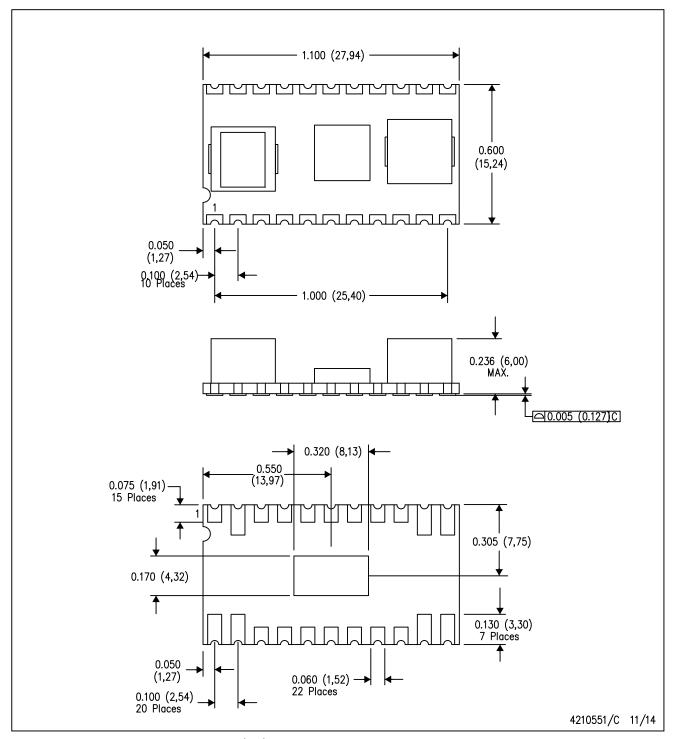
EFS (R-PDSS-T22)

SINGLE SIDED MODULE



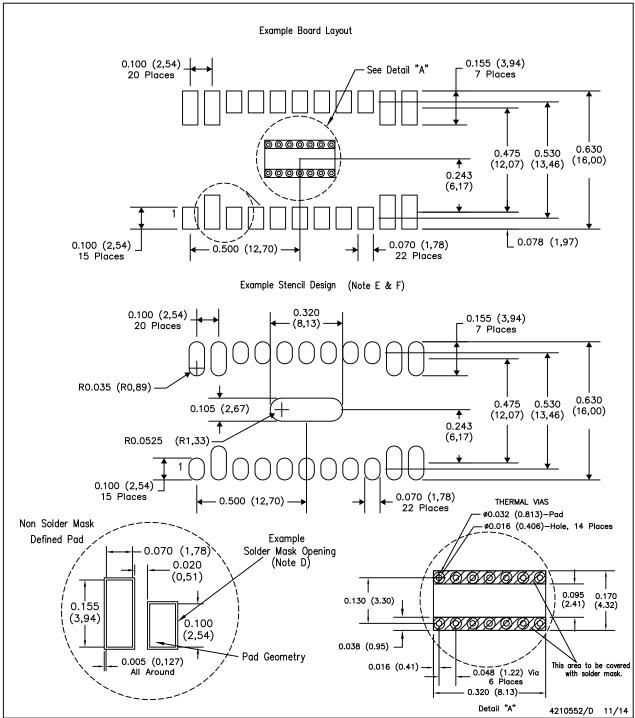
NOTES: A. All linear dimensions are in inches (mm).

- B. This drawing is subject to change without notice.
 C. 2 place decimals are ±0.030 (±0,76mm).
 D. 3 place decimals are ±0.010 (±0,25mm).



EFS (R-PDSS-T22)

SINGLE SIDED MODULE



- NOTES: A. B.

 - All linear dimensions are in inches & millimeters.
 This drawing is subject to change without notice.
 This package is designed to be soldered to a thermal pad on the board. This pad must be at ground potential and be connected to an internal ground plane with multiple thermal vias.

 - Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

 Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - Paste screen thickness: 0.006 (0,15).
 - 3 place decimals are ±0.010 (±0.25)



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